Title (en)
SEMICONDUCTOR DEVICE

Title (de)
HALBLEITER-BAUELEMENT

Title (fr)
COMPOSANT A SEMI-CONDUCTEUR

Publication
EP 0907882 A1 19990414 (DE)

Application
EP 97931627 A 19970620

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Abstract (en)
[origin: DE19626081A1] The invention pertains to a semiconductor device consisting of a chip carrier (5) which is made of an electrically insulating material and has an approximately flat chip carrier surface (4) on which is mounted a semiconductor chip (6) with a pressure sensor, and of electrode leads (7) which pass through the chip carrier (5) and are electrically connected to the semiconductor chip (6) in a surface-mountable arrangement. The chip carrier (5) can be periodically closed by a protective cap (28) covering the pressure sensor.

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G01L 9/00

IPC 8 full level
G01L 9/00 (2006.01)

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Citation (search report)
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